

| U.S. PATENT DOCUMENTS |    |                 |          |               |       |               |                |
|-----------------------|----|-----------------|----------|---------------|-------|---------------|----------------|
| EXAMINER<br>INITIAL   |    | DOCUMENT<br>NO. | DATE     | NAME          | CLASS | SUB-<br>CLASS | FILING<br>DATE |
| FH                    | AA | 5,936,642       | 8/10/99  | Yumoto et al. | 345   | 504           | 3/27/97        |
| FH                    | AB | 6,008,822       | 12/28/99 | Yumoto et al. | 345   | 507           | 5/21/99        |
| TH                    | AC | 5,809,240       | 9/15/98  | Kumagai       | 395   | 200           | 11/19/96       |
|                       | AD |                 |          |               |       |               |                |
|                       | AE |                 |          |               |       |               |                |
|                       | AF |                 |          |               |       |               |                |

| FOREIGN PATENT DOCUMENTS |    |                |          |         |       |           |                                                                           |  |
|--------------------------|----|----------------|----------|---------|-------|-----------|---------------------------------------------------------------------------|--|
|                          |    | DOCUMENT NO.   | DATE     | COUNTRY | CLASS | SUB-CLASS | TRANSLATION<br>YES NO                                                     |  |
| TH                       | AG | JP-A-11-353470 | 12/24/99 | Japan   |       |           | Abst                                                                      |  |
| TH                       | AH | JP-A-11-85967  | 3/30/99  | Japan   |       |           | Abst                                                                      |  |
| TH                       | AI | JP-A-8-16766   | 1/19/96  | Japan   |       |           | Abst                                                                      |  |
| TH                       | AJ | JP-A-9-319788  | 12/12/97 | Japan   |       |           | Corresponding<br>U.S. Patent<br>5,936,642 and<br>U.S. Patent<br>6,008,822 |  |
| TH                       | AK | JP-A-7-98726   | 4/11/95  | Japan   |       |           | Corresponding<br>U.S. Patent<br>5,809,240                                 |  |
|                          | AL |                |          |         |       |           |                                                                           |  |

| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.) |    |  |
|-------------------------------------------------------------------------|----|--|
|                                                                         | AM |  |
|                                                                         | AN |  |
|                                                                         | AO |  |

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| EXAMINER                                                                                                                                                                                                                                 | <i>T. H. H. H. H. H.</i> | DATE CONSIDERED | <i>Oct. 1, 2003</i> |
| EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. |                          |                 |                     |